DB6X314K

Silicon epitaxial planar type

For high speed switching circuits

■ Features

- Short reverse recovery time t_{rr}
- Small reverse current I_R
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

■ Marking Symbol: 4X

■ Basic Part Number

Triple DB2J314 (Parallel)

Packaging

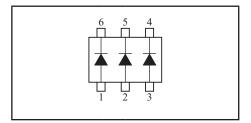
DB6X314K0R Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings T_a = 25°C

Parameter	Symbol	Rating	Unit	
Reverse voltage	V_R	30	V	
Maximum peak reverse voltage	V _{RM}	30	V	
Fowerd current *1	I_{F}	30	mA	
Peak forward current *1	I_{FM}	150	mA	
Junction temperature	T_j	125	°C	
Operating ambient temperature	T _{opr}	-40 to +85	°C	
Storage temperature	T _{stg}	-55 to +125	°C	

Note) *1: Value for single diode

Unit: mm 2.9 0.13 0.3 2 0.3 (0.95)(0.95)1: Anode-1 4: Cathode-3 2: Anode-2 5: Cathode-2 3: Anode-3 6: Cathode-1 Panasonic Mini6-G4-B **JEITA** SC-74 Code SOT-457

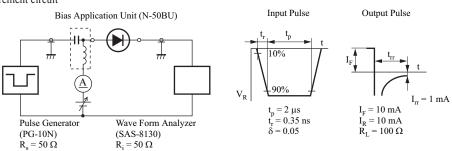


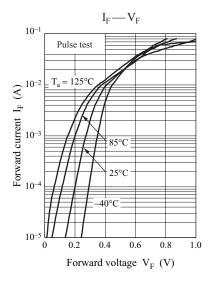
■ Electrical Characteristics $T_a = 25$ °C±3°C

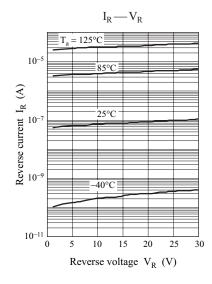
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V_{F1}	$I_F = 1 \text{ mA}$			0.4	V
	V_{F2}	$I_F = 30 \text{ mA}$			1.0	
Reverse current	I_R	$V_R = 30 \text{ V}$			300	nA
Terminal capacitance	C _t	$V_R = 10 \text{ V}, f = 1 \text{ MHz}$		1.5		pF
Reverse recovery time *1	t _{rr}	$I_F = I_R = 10 \text{ mA}, I_{rr} = 1 \text{ mA}, R_L = 100 \Omega$		1.0		ns

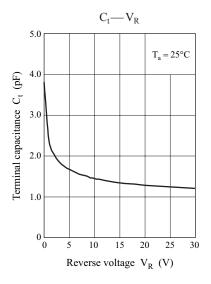
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 2 GHz
 - $*1: t_{rr}$ measurement circuit





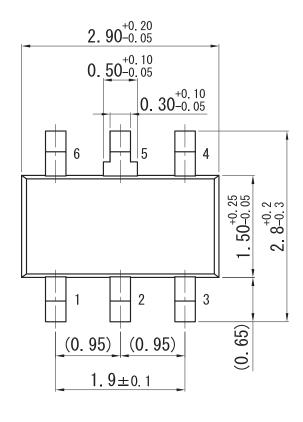


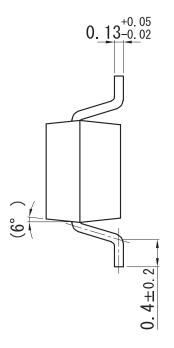


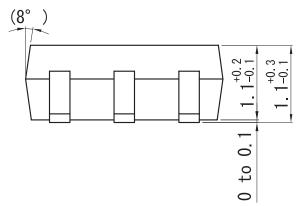
Ver. CED 2

Mini6-G4-B

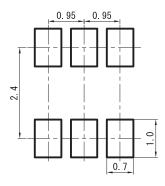
Unit: mm







■ Land Pattern (Reference) (Unit: mm)



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